

Application No. 09/862,593  
Docket No.: Shipley 03-16 (ACT - 135)

Art Unit: 1756  
Examiner: Sagar, Kripa

## II. AMENDMENT

Please amend the application as follows.

### In the specification:

I. Please amend paragraph [0015] to read as follows.

[0015] In addition, this is a continuation-in-part (CIP) of co-pending application Serial No. ~~09/853,250~~ 09/858,999, filed May 16, 2001, and entitled "Multi-Level Optical Structure And Method Of Manufacture", which in turn is a continuation-in-part (CIP) of co-pending application Serial No. 09/853,250, filed May 9, 2001, and entitled "Multi-Level Lithography Masks", which in turn claims the benefit of the following U.S. Provisional Patent Applications: Serial Number 60/202,596, entitled "Multilevel Contact Mask For Patterning Multilevel Substrates", filed May 9, 2000; Serial Number 60/204,473, entitled "Single Mask Process for Patterning Integrated Optic Waveguides, Metallizations and Micromachined Features", filed May 16, 2000, and Serial Number 60/257,021, entitled "Alternative Embodiment For Making The Multilevel Contact Mask", filed December 20, 2000. The entireties of these applications are incorporated herein by reference.